

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1-15

Claim 16 (new): A method for manufacturing a semiconductor integrated circuit device comprising the steps of:

forming a plurality of circuit patterns on a substrate;

bonding a plurality of semiconductor integrated circuit chips onto a first surface of the substrate having the circuit patterns formed thereon, and connecting electrodes of the semiconductor integrated circuit chips to each of the circuit patterns;

applying a first seal resin onto each of the semiconductor integrated circuit chips;

disposing a first reinforcement metal plate above the first seal resin;

applying a second seal resin onto a second reinforcement metal plate;

disposing the second reinforcement metal plate on a second surface of the substrate with the second seal resin therebetween;

pressurizing the first and second seal resins via the first and second reinforcement metal plates so as to let flow the first seal resin along a peripheral faces of each of the semiconductor integrated circuit chips;

hardening the seal resins flown along the peripheral faces of the semiconductor integrated circuit chips; and

thereafter dividing the substrate into a semiconductor integrated circuit device at every semiconductor integrated circuit chip.

Claim 17 (new): A method for manufacturing a semiconductor integrated circuit card comprising the steps of:

forming a plurality of circuit patterns on a substrate;

bonding a plurality semiconductor integrated circuit chips onto a first surface of the substrate having the circuit patterns formed thereon, and connecting electrodes of the semiconductor integrated circuit chips to each of the circuit patterns;

applying a first seal resin onto each of the semiconductor integrated circuit chips;

disposing a first reinforcement metal plate above the first seal resin;

applying a second seal resin onto a second reinforcement metal plate;

disposing the second reinforcement metal plate on a second surface of the substrate with the second seal resin therebetween;

pressurizing the first and second seal resins via the first and second reinforcement metal plates so as to let flow the first seal resin along peripheral faces of each of the semiconductor integrated circuit chips;

hardening the seal resins flown along the peripheral faces of the semiconductor integrated circuit chips;

dividing the substrate into a semiconductor integrated circuit device at every semiconductor integrated circuit chip;

disposing an individually divided semiconductor integrated circuit chip on a roll film and coating the same;

heating a thin film on which the semiconductor integrated circuit chip is coated with the thin film;

manufacturing a card connected plate in which a plurality of semiconductor integrated circuit chips are connected in line; and

dividing the card connected plate into an individual semiconductor integrated circuit card.